



STPS60L15CW

LOW DROP OR-ing POWER SCHOTTKY DIODE

MAJOR PRODUCT CHARACTERISTICS

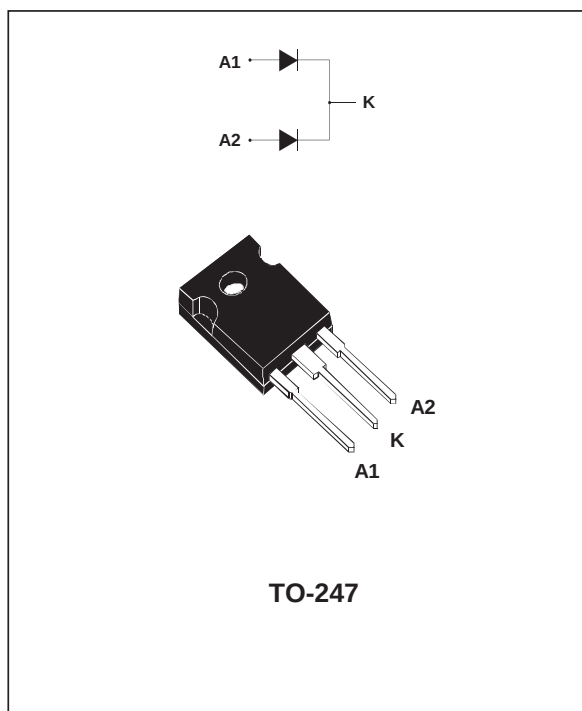
$I_{F(AV)}$	2 x 30 A
V_{RRM}	15 V
$T_j (max)$	125°C
$V_F (max)$	0.33 V

FEATURES AND BENEFITS

- VERY LOW FORWARD VOLTAGE DROP FOR LESS POWER DISSIPATION AND REDUCED HEATSINK SIZE
- OPERATION JUNCTION TEMPERATURE: 125°C
- REVERSE VOLTAGE SUITED TO OR-ing OF 3V, 5V and 12V RAILS
- AVALANCHE CAPABILITY SPECIFIED

DESCRIPTION

Dual center tap schottky rectifier packaged in TO-247 and suited for N+1 redundancy operations, this device has an optimized forward voltage drop to reduce the power losses in the application.



TO-247

ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			15	V
I _{F(RMS)}	RMS forward current			40	A
I _{F(AV)}	Average forward current	Tcase = 115°C δ = 0.5	Per diode	30	A
			Per device	60	
I _{FSM}	Surge non repetitive forward current	tp = 10 ms Sinusoidal		400	A
I _{RRM}	Peak repetitive reverse current	tp = 2μs F = 1kHz		2	A
I _{RSM}	Non repetitive peak reverse current	tp = 100μs		3	A
P _{ARM}	Repetitive peak avalanche power	tp = 1μs Tj = 25°C		24000	W
T _{stg}	Storage temperature range			- 65 to + 150	°C
T _j	Maximum operating junction temperature *			125	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/μs

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink

STPS60L15CW

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	0.8	$^{\circ}\text{C/W}$
		Total	0.55	
$R_{th(c)}$	Coupling		0.3	$^{\circ}\text{C/W}$

When the diodes 1 and 2 are used simultaneously:
 $T_j (\text{diode 1}) = P (\text{diode 1}) \times R_{th(j-c)} (\text{per diode}) + P (\text{diode 2}) \times R_{th(c)}$

STATIC ELECTRICAL CHARACTERISTICS (Per diode)

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I_R^*	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			16	mA
		$T_j = 100^{\circ}\text{C}$			0.35	0.85	A
V_F^*	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 30\text{ A}$			0.41	V
		$T_j = 25^{\circ}\text{C}$	$I_F = 60\text{ A}$			0.49	
		$T_j = 125^{\circ}\text{C}$	$I_F = 30\text{ A}$		0.27	0.33	
		$T_j = 125^{\circ}\text{C}$	$I_F = 60\text{ A}$		0.39	0.44	

Pulse test : * $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:
 $P = 0.22 \times I_{F(AV)} + 0.0036 I_{F(RMS)}^2$

Fig. 1: Conduction losses versus average current).

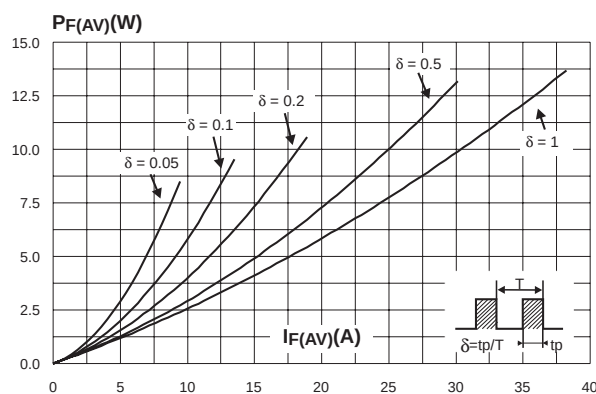


Fig. 3: Normalized avalanche power derating versus pulse duration.

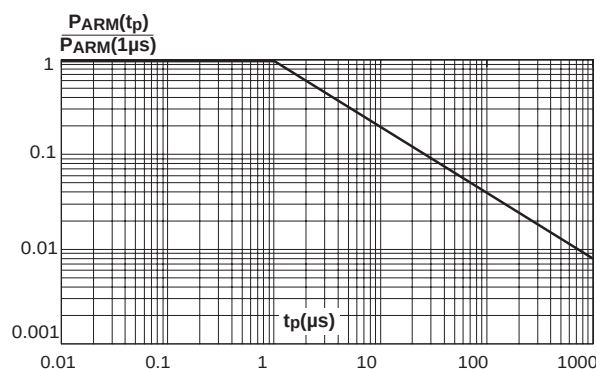


Fig. 2: Average forward current versus ambient temperature ($\delta=0.5$).

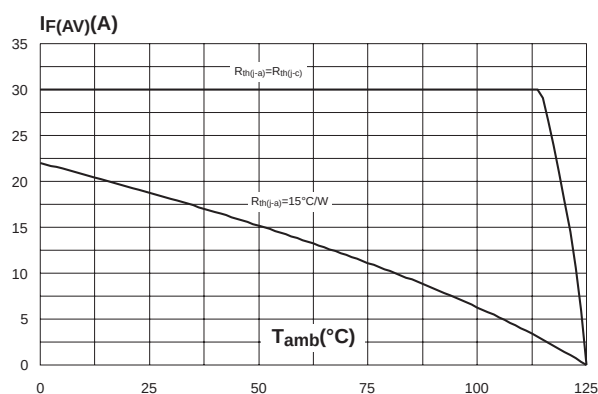


Fig. 4: Normalized avalanche power derating versus junction temperature.

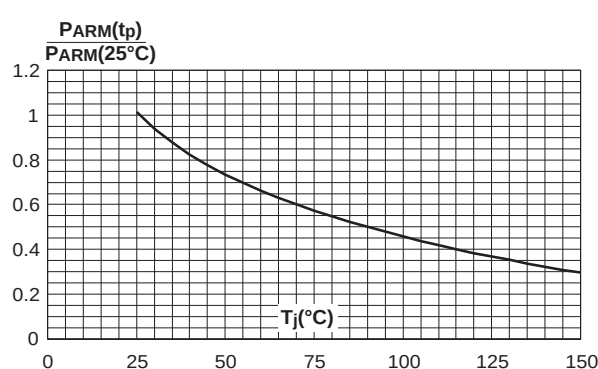


Fig. 5: Non repetitive surge peak forward current versus overload duration (maximum values).

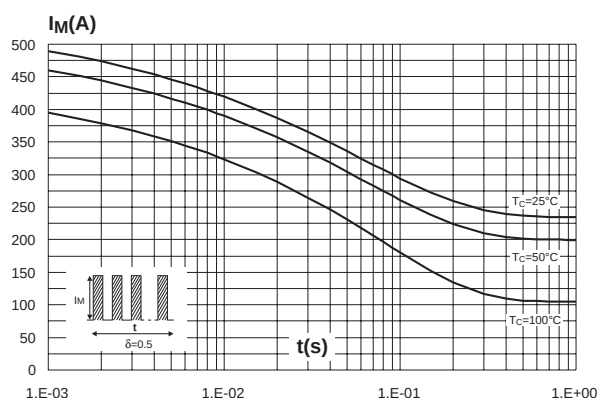


Fig. 6: Relative variation of thermal impedance junction to case versus pulse duration.

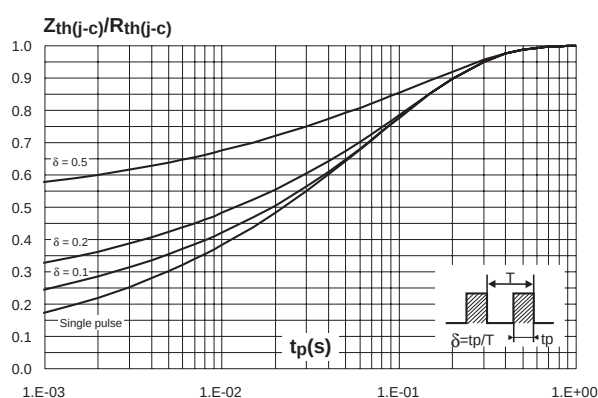


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values).

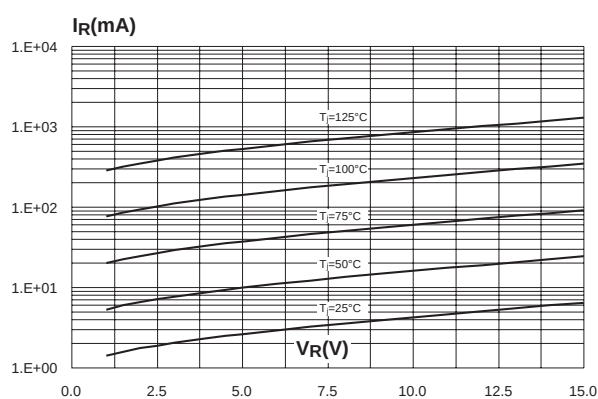


Fig. 8: Junction capacitance versus reverse voltage applied (typical values).

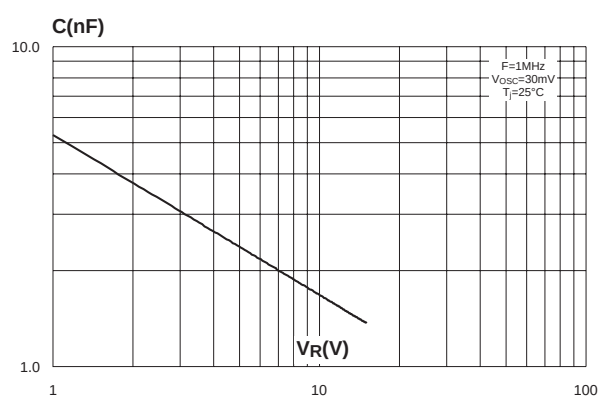
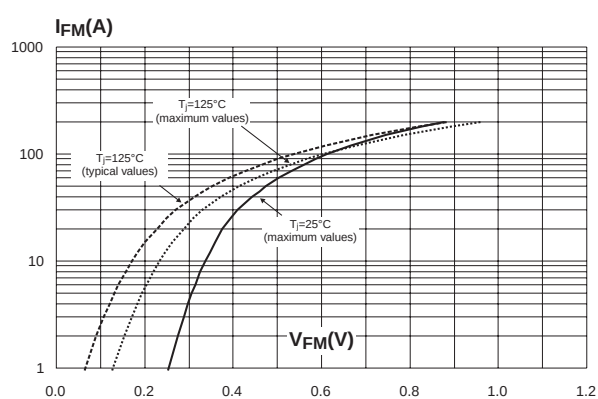


Fig. 9: Forward voltage drop versus forward current.



STPS60L15CW**PACKAGE MECHANICAL DATA**
TO-247

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F1		3.00			0.118	
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
F4	3.00		3.40	0.118		0.133
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

- Cooling method: C
- Recommended torque value: 0.8 m.N
- Maximum torque value: 1.0 m.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS60L15CW	STPS60L15CW	TO-247	4.4 g.	30	Tube

- Epoxy meets UL94,V0

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